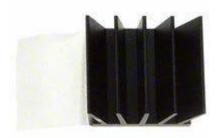
BGA Heat Sink - High Performance ASIC Cooling





ATS Part#:

Description:

ATS-56003-C1-R0

15.00 x 15.00 x 9.00 mm BGA Heat Sink - High Performance ASIC Cooling

Heat Sink Type: Heat Sink Attachment: Equivalent Part Number: ATS-56003-C3-R0

ASIC Cooling Thermal Tape

*Image above is for illustration purpose only.

Features & Benefits

- maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling .
- Designed specifically for ASIC package and their unique cooling requirements •
- Comes preassembled with high performance thermal interface material •

Thermal Performance

		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	12 °C/W	10 °C/W	7.8 °C/W	6.9 °C/W	6 °C/W	5.7 °C/W	5.1 °C/W
	Ducted Flow	9	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	ТІМ	Finish
	15.00 mm	15.00 mm	9.00 mm	17.8 mm	T412	BLACK-ANODIZED
Image above is for illustration purpose only.	 Dimension ATS-5600 (Saint-Go Thermal p application ATS resen performar ATS certifi 	03-C3-R0 is the example bain C675). performance data ar n. rves the right to upd nce.	height from the botto of heat sink assemb e provided for refere ate or change its pro	om of the base to the ly with an equivalen ence only. Actual per oducts without notice S-6 and REACH cor able.	formance to impro	interface material e may vary by

For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), sales@qats.com or www.qats.com.

